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SASAKI(10) **Pub. No.: US 2022/0385266 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **ELECTRONIC COMPONENT HOUSING
PACKAGE, ELECTRONIC DEVICE, AND
ELECTRONIC MODULE****Publication Classification**(51) **Int. Cl.***H03H 9/05* (2006.01)*H03H 9/10* (2006.01)*H03H 9/19* (2006.01)(52) **U.S. Cl.**CPC *H03H 9/0523* (2013.01); *H03H 9/1021*
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ABSTRACT

An electronic component housing package includes: an insulating substrate including a main surface; an external connection conductor including a portion exposed at the main surface; and an inner layer conductor located inside of the external connection conductor in a thickness direction of the insulating substrate, in which the external connection conductor includes a protruding portion extending toward the inner layer conductor, and the protruding portion is in contact with the inner layer conductor.

